



FIGURE 1.12 The chip manufacturing process. After being sliced from the silicon ingot, blank wafers are put through 20 to 40 steps to create patterned wafers (see Figure 1.13). These patterned wafers are then tested with a wafer tester, and a map of the good parts is made. Then, the wafers are diced into dies (see Figure 1.9). In this figure, one wafer produced 20 dies, of which 17 passed testing. (X means the die is bad.) The yield of good dies in this case was 17/20, or 85%. These good dies are then bonded into packages and tested one more time before shipping the packaged parts to customers. One bad packaged part was found in this final test.